# **GP1S25**

#### **■** Features

1. Side lead ultra-compact transmission type

2. Conforming to solder reflow

Pre-heat: 160 °C, MAX. 120 sec Reflow: (200 °C, MAX. 60 sec) 240 °C, MAX. 10 sec)

3. Slit : 0.3 mm 4. Gap : 1.6 mm

# ■ Applications

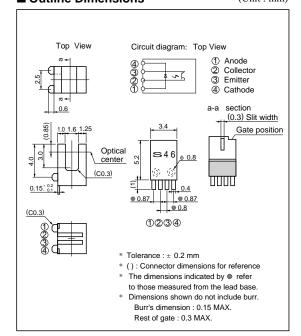
1. CD-ROM drives

2. FDDs

# **Side Lead Type Ultra-compact Photointerrupter**

#### **■** Outline Dimensions

(Unit: mm)



## ■ Absolute Maximum Ratings

 $(Ta=25^{\circ}C)$ 

- Abbolato maximum ratingo						
	Parameter	Symbol	Rating	Unit		
	Forward current	$I_{\mathrm{F}}$	50	mA		
Input	Reverse voltage	$V_R$	6	V		
	Power dissipation	P	75	mW		
	Collector-emitter voltage	V <sub>CEO</sub>	35	V		
0	Emitter-collector voltage	V <sub>ECO</sub>	6	V		
Output	Collector current	Ic	20	mA		
	Collector power dissipation	Pc	75	mW		
	Total power dissipation		100	mW		
	Operating temperature		- 25 to + 85	°C		
	Storage temperature		- 40 to + 100	°C		
	*1Soldering temperature		260	°C		

<sup>\*1</sup> Soldering time: For 3 seconds (hand soldering)



### **■** Electro-optical Characteristics

(Ta=25 °C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Lamust	Forward voltage		V <sub>F</sub>	$I_{\mathrm{F}}=20mA$	-	1.2	1.4	V
Input	Reverse current		$I_R$	$V_R = 3V$	-	-	10	μΑ
Output	Dark current		I <sub>CEO</sub>	$V_{CE} = 20V$	-	-	100	nA
	Collector current		Ic	$V_{CE} = 5V$ , $I_F = 5mA$	50	-	300	μΑ
Transfer	Collector-emitter saturation voltage		V CE(sat)	$I_F=10mA,I_C=50\mu\;A$	-	-	0.4	V
characteristics	D	Rise time	t <sub>r</sub>	$V_{CE}=5V,~I_{C}=100\mu$ A	-	35	100	μs
	Response time	Fall time	$t_{\mathrm{f}}$	$R_{\rm L}=1~000~\Omega$	-	35	100	μs

Fig. 1 Forward Current vs. Ambient Temperature

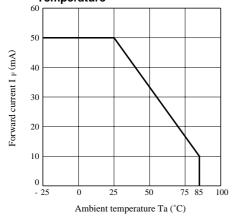


Fig. 3 Forward Current vs. Forward Voltage

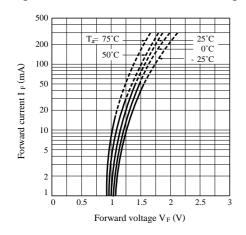


Fig. 2 Power dissipation vs. Ambient Temperature

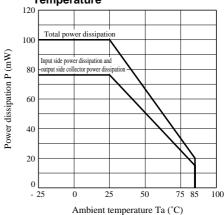


Fig. 4 Collector Current vs. Forward Current

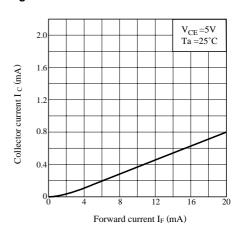


Fig. 5 Collector Current vs. Collector-emitter Voltage

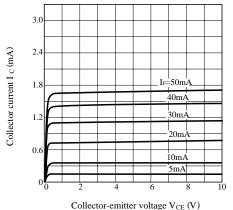


Fig. 7 Collector-emitter Saturation Voltage vs. Ambient Temperature

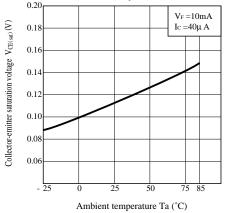


Fig. 9 Response Time vs. Load Resistance

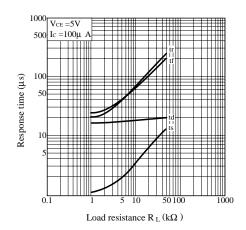


Fig. 6 Relative Collector Current vs.

Ambient Temperature

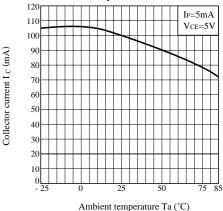
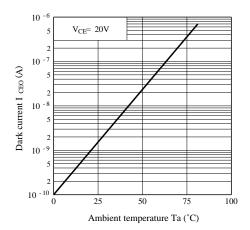


Fig. 8 Dark Current vs. Ambient Temperature



**Test Circuit for Response Time** 

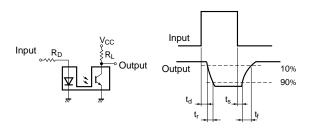
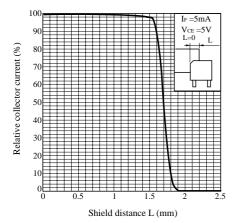
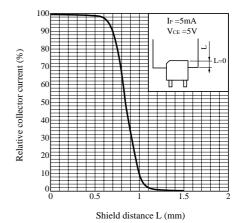


Fig. 10 Detecting Position Characteristics (1)



 $\bullet\,$  Please refer to the chapter "Precautions for Use".

Fig. 11 Detecting Position Characteristics (2)



#### **NOTICE**

- •The circuit application examples in this publication are provided to explain representative applications of SHARP devices and are not intended to guarantee any circuit design or license any intellectual property rights. SHARP takes no responsibility for any problems related to any intellectual property right of a third party resulting from the use of SHARP's devices.
- •Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device. SHARP reserves the right to make changes in the specifications, characteristics, data, materials, structure, and other contents described herein at any time without notice in order to improve design or reliability. Manufacturing locations are also subject to change without notice.
- Observe the following points when using any devices in this publication. SHARP takes no responsibility for damage caused by improper use of the devices which does not meet the conditions and absolute maximum ratings to be used specified in the relevant specification sheet nor meet the following conditions:
  - (i) The devices in this publication are designed for use in general electronic equipment designs such as:
  - Personal computers
  - Office automation equipment
  - Telecommunication equipment [terminal]
  - Test and measurement equipment
  - Industrial control
  - Audio visual equipment
  - Consumer electronics
  - (ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:
  - Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
  - Traffic signals
  - Gas leakage sensor breakers
  - Alarm equipment
  - Various safety devices, etc.
  - (iii)SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:
  - Space applications
  - Telecommunication equipment [trunk lines]
  - Nuclear power control equipment
  - Medical and other life support equipment (e.g., scuba).
- •Contact a SHARP representative in advance when intending to use SHARP devices for any "specific" applications other than those recommended by SHARP or when it is unclear which category mentioned above controls the intended use.
- •If the SHARP devices listed in this publication fall within the scope of strategic products described in the Foreign Exchange and Foreign Trade Control Law of Japan, it is necessary to obtain approval to export such SHARP devices.
- •This publication is the proprietary product of SHARP and is copyrighted, with all rights reserved. Under the copyright laws, no part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, for any purpose, in whole or in part, without the express written permission of SHARP. Express written permission is also required before any use of this publication may be made by a third party.
- Contact and consult with a SHARP representative if there are any questions about the contents of this
  publication.